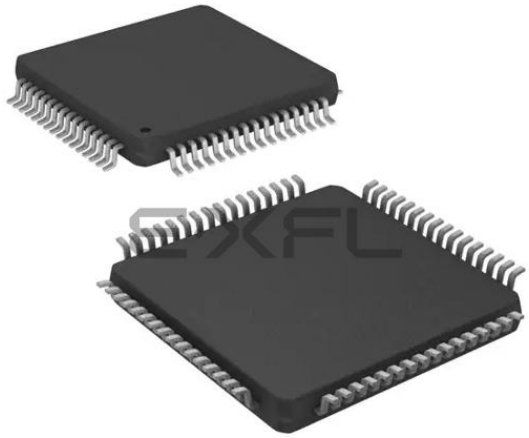

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f6310t-i-pt

1.2 Other Special Features

- **Memory Endurance:** The Flash cells for program memory are rated to last for approximately a thousand erase/write cycles. Data retention without refresh is conservatively estimated to be greater than 100 years.
- **External Memory Interface:** For those applications where more program or data storage is needed, the PIC18F8310/8410 devices provide the ability to access external memory devices. The memory interface is configurable for both 8-bit and 16-bit data widths and uses a standard range of control signals to enable communication with a wide range of memory devices. With their 21-bit program counters, the 80-pin devices can access a linear memory space of up to 2 Mbytes.
- **Extended Instruction Set:** The PIC18F6310/6410/8310/8410 family introduces an optional extension to the PIC18 instruction set, which adds 8 new instructions and an Indexed Addressing mode. This extension, enabled as a device configuration option, has been specifically designed to optimize re-entrant application code originally developed in high-level languages such as ‘C’.
- **Enhanced Addressable USART:** This serial communication module is capable of standard RS-232 operation and provides support for the LIN/J2602 bus protocol. Other enhancements include Automatic Baud Rate Detection (ABD) and a 16-bit Baud Rate Generator for improved resolution. When the microcontroller is using the internal oscillator block, the EUSART provides stable operation for applications that talk to the outside world, without using an external crystal (or its accompanying power requirement).
- **10-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, and thus, reduces code overhead.
- **Extended Watchdog Timer (WDT):** This enhanced version incorporates a 16-bit prescaler, allowing a time-out range from 4 ms to over 2 minutes that is stable across operating voltage and temperature.

1.3 Details on Individual Family Members

Devices in the PIC18F6310/6410/8310/8410 family are available in 64-pin (PIC18F6310/8310) and 80-pin (PIC18F6410/8410) packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2, respectively.

The devices are differentiated from each other in three ways:

1. Flash Program Memory: 8 Kbytes in PIC18FX310 devices, 16 Kbytes in PIC18FX410 devices.
2. I/O Ports: 7 bidirectional ports on 64-pin devices, 9 bidirectional ports on 80-pin devices.
3. External Memory Interface: present on 80-pin devices only.

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

Like all Microchip PIC18 devices, members of the PIC18F6310/6410/8310/8410 family are available as both standard and low-voltage devices. Standard devices with Flash memory, designated with an “F” in the part number (such as PIC18F6310), accommodate an operating V_{DD} range of 4.2V to 5.5V. Low-voltage parts, designated by “LF” (such as PIC18LF6410), function over an extended V_{DD} range of 2.0V to 5.5V.

3.0 OSCILLATOR CONFIGURATIONS

3.1 Oscillator Types

PIC18F6310/6410/8310/8410 devices can be operated in ten different oscillator modes. The user can program the Configuration bits, FOSC<3:0>, in Configuration Register 1H to select one of these ten modes:

1. LP Low-Power Crystal
2. XT Crystal/Resonator
3. HS High-Speed Crystal/Resonator
4. HSPLL High-Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor with FOSC/4 output on RA6
6. RCIO External Resistor/Capacitor with I/O on RA6
7. INTIO1 Internal Oscillator with FOSC/4 output on RA6 and I/O on RA7
8. INTIO2 Internal Oscillator with I/O on RA6 and RA7
9. EC External Clock with FOSC/4 output
10. ECIO External Clock with I/O on RA6

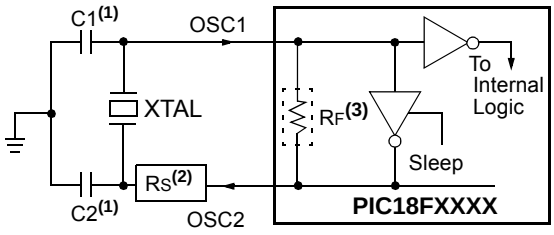
3.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 3-1 shows the pin connections.

The oscillator design requires the use of a parallel resonant crystal.

Note:	Use of a series resonant crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 3-1: CRYSTAL/CERAMIC RESONATOR OPERATION (XT, LP, HS OR HSPLL CONFIGURATION)



Note 1: See Table 3-1 and Table 3-2 for initial values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the oscillator mode chosen.

TABLE 3-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	56 pF 47 pF 33 pF	56 pF 47 pF 33 pF
HS	8.0 MHz 16.0 MHz	27 pF 22 pF	27 pF 22 pF

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following Table 3-2 for additional information.

Resonators Used:	
455 kHz	4.0 MHz
2.0 MHz	8.0 MHz
16.0 MHz	

3.4 RC Oscillator

For timing-insensitive applications, the "RC" and "RCIO" device options offer additional cost savings. The actual oscillator frequency is a function of several factors:

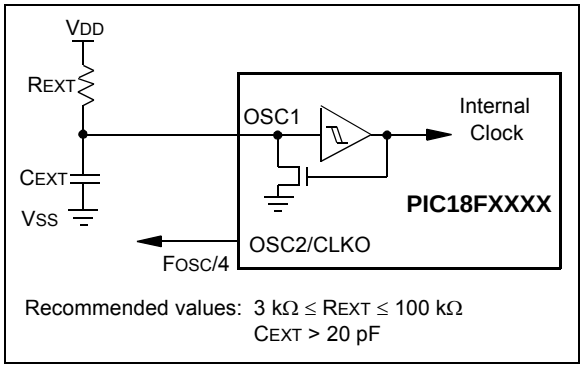
- Supply voltage
- Values of the external resistor (REXT) and capacitor (CEXT)
- Operating temperature

Given the same device, operating voltage and temperature and component values, there will also be unit-to-unit frequency variations. These are due to factors such as:

- Normal manufacturing variation
- Difference in lead frame capacitance between package types (especially for low CEXT values)
- Variations within the tolerance of limits of REXT and CEXT

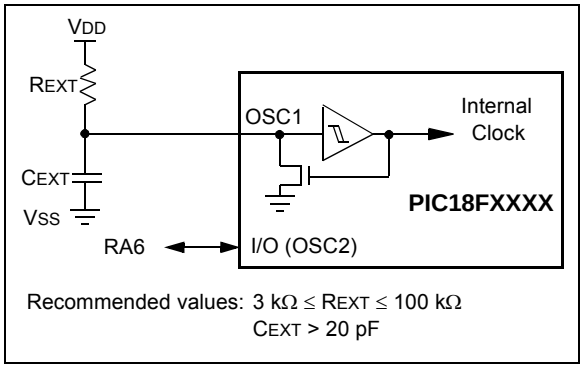
In the RC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 3-5 shows how the R/C combination is connected.

FIGURE 3-5: RC OSCILLATOR MODE



The RCIO Oscillator mode (Figure 3-6) functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

FIGURE 3-6: RCIO OSCILLATOR MODE



3.5 PLL Frequency Multiplier

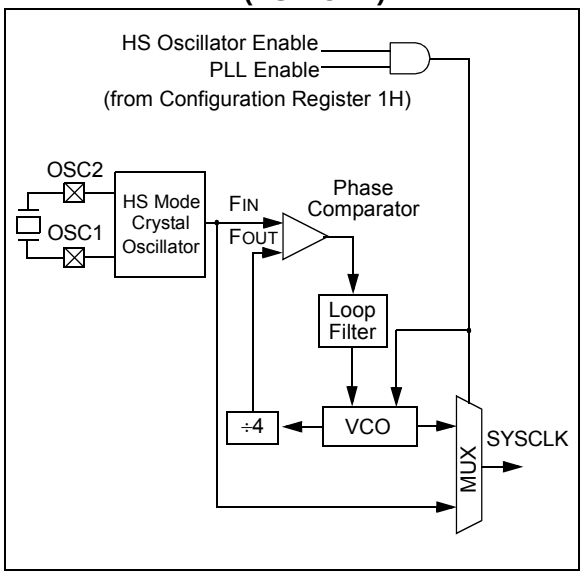
A Phase Locked Loop (PLL) circuit is provided as an option for users who want to use a lower frequency oscillator circuit, or to clock the device up to its highest rated frequency from a crystal oscillator. This may be useful for customers who are concerned with EMI due to high-frequency crystals, or users who require higher clock speeds from an internal oscillator.

3.5.1 HSPLL OSCILLATOR MODE

The HSPLL mode makes use of the HS Oscillator mode for frequencies up to 10 MHz. A PLL then multiplies the oscillator output frequency by 4 to produce an internal clock frequency up to 40 MHz.

The PLL is only available to the crystal oscillator when the FOSC<3:0> Configuration bits are programmed for HSPLL mode (= 0110).

FIGURE 3-7: PLL BLOCK DIAGRAM (HS MODE)



3.5.2 PLL AND INTOSC

The PLL is also available to the internal oscillator block in selected oscillator modes. In this configuration, the PLL is enabled in software and generates a clock output of up to 32 MHz. The operation of INTOSC with the PLL is described in **Section 3.6.4 "PLL in INTOSC Modes"**.

6.3 Data Memory Organization

Note: The operation of some aspects of data memory are changed when the PIC18 extended instruction set is enabled. See **Section 6.5 "Data Memory and the Extended Instruction Set"** for more information.

The data memory in PIC18 devices is implemented as static RAM. Each register in the data memory has a 12-bit address, allowing up to 4096 bytes of data memory. The memory space is divided into as many as 16 banks that contain 256 bytes each. PIC18F6310/6410/8310/8410 devices implement only 3 complete banks, for a total of 768 bytes. Figure 6-6 shows the data memory organization for the devices.

The data memory contains Special Function Registers (SFRs) and General Purpose Registers (GPRs). The SFRs are used for control and status of the controller and peripheral functions, while GPRs are used for data storage and scratchpad operations in the user's application. Any read of an unimplemented location will read as '0's.

The instruction set and architecture allow operations across all banks. The entire data memory may be accessed by Direct, Indirect or Indexed Addressing modes. Addressing modes are discussed later in this section.

To ensure that commonly used registers (SFRs and select GPRs) can be accessed in a single cycle, PIC18 devices implement an Access Bank. This is a 256-byte memory space that provides fast access to SFRs and the lower portion of GPR Bank 0 without using the BSR. **Section 6.3.2 "Access Bank"** provides a detailed description of the Access RAM.

6.3.1 BANK SELECT REGISTER

Large areas of data memory require an efficient addressing scheme to make rapid access to any address possible. Ideally, this means that an entire address does not need to be provided for each read or write operation. For PIC18 devices, this is accomplished with a RAM banking scheme. This divides the memory space into16 contiguous banks of 256 bytes. Depending on the instruction, each location can be addressed directly by its full 12-bit address, or an 8-bit low-order address and a 4-bit Bank Pointer.

Most instructions in the PIC18 instruction set make use of the Bank Pointer, known as the Bank Select Register (BSR). This SFR holds the 4 Most Significant bits of a location's address; the instruction itself includes the 8 Least Significant bits. Only the four lower bits of the BSR are implemented (BSR<3:0>). The upper four bits are unused; they will always read '0' and cannot be written to. The BSR can be loaded directly by using the MOVLB instruction.

The value of the BSR indicates the bank in data memory; the 8 bits in the instruction show the location in the bank and can be thought of as an offset from the bank's lower boundary. The relationship between the BSR's value and the bank division in data memory is shown in Figure 6-7.

Since up to 16 registers may share the same low-order address, the user must always be careful to ensure that the proper bank is selected before performing a data read or write. For example, writing what should be program data to an 8-bit address of F9h while the BSR is 0Fh will end up resetting the program counter.

While any bank can be selected, only those banks that are actually implemented can be read or written to. Writes to unimplemented banks are ignored, while reads from unimplemented banks will return '0's. Even so, the STATUS register will still be affected as if the operation was successful. The data memory map in Figure 6-6 indicates which banks are implemented.

In the core PIC18 instruction set, only the MOVFF instruction fully specifies the 12-bit address of the source and target registers. This instruction ignores the BSR completely when it executes. All other instructions include only the low-order address as an operand and must use either the BSR or the Access Bank to locate their target registers.

TABLE 6-3: REGISTER FILE SUMMARY (PIC18F6310/6410/8310/8410)

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Details on page:
TOSU	—	—	—	Top-of-Stack Upper Byte (TOS<20:16>)					---0 0000	63, 70
TOSH	Top-of-Stack High Byte (TOS<15:8>)								0000 0000	63, 70
TOSL	Top-of-Stack Low Byte (TOS<7:0>)								0000 0000	63, 70
STKPTR	STKFUL(6)	STKUNF(6)	—	Return Stack Pointer					00-0 0000	63, 71
PCLATU	—	—	—	Holding Register for PC<20:16>					---0 0000	63, 70
PCLATH	Holding Register for PC<15:8>								0000 0000	63, 70
PCL	PC Low Byte (PC<7:0>)								0000 0000	63, 70
TBLPTRU	—	—	bit 21	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					--00 0000	63, 93
TBLPTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								0000 0000	63, 93
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								0000 0000	63, 93
TABLAT	Program Memory Table Latch								0000 0000	63, 93
PRODH	Product Register High Byte								xxxx xxxx	63, 107
PRODL	Product Register Low Byte								xxxx xxxx	63, 107
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	63, 111
INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	INTEDG3	TMR0IP	INT3IP	RBIP	1111 1111	63, 112
INTCON3	INT2IP	INT1IP	INT3IE	INT2IE	INT1IE	INT3IF	INT2IF	INT1IF	1100 0000	63, 113
INDF0	Uses contents of FSR0 to address data memory – value of FSR0 not changed (not a physical register)								N/A	63, 85
POSTINC0	Uses contents of FSR0 to address data memory – value of FSR0 post-incremented (not a physical register)								N/A	63, 85
POSTDEC0	Uses contents of FSR0 to address data memory – value of FSR0 post-decremented (not a physical register)								N/A	63, 85
PREINC0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register)								N/A	63, 85
PLUSW0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register), value of FSR0 offset by W								N/A	63, 85
FSR0H	—	—	—	—	Indirect Data Memory Address Pointer 0 High Byte				---- xxxx	63, 85
FSR0L	Indirect Data Memory Address Pointer 0 Low Byte								xxxx xxxx	63, 85
WREG	Working Register								xxxx xxxx	63
INDF1	Uses contents of FSR1 to address data memory – value of FSR1 not changed (not a physical register)								N/A	63, 85
POSTINC1	Uses contents of FSR1 to address data memory – value of FSR1 post-incremented (not a physical register)								N/A	63, 85
POSTDEC1	Uses contents of FSR1 to address data memory – value of FSR1 post-decremented (not a physical register)								N/A	63, 85
PREINC1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register)								N/A	63, 85
PLUSW1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register), value of FSR1 offset by W								N/A	63, 85
FSR1H	—	—	—	—	Indirect Data Memory Address Pointer 1 High Byte				---- xxxx	63, 85
FSR1L	Indirect Data Memory Address Pointer 1 Low Byte								xxxx xxxx	63, 85
BSR	—	—	—	—	Bank Select Register				---- 0000	63, 75
INDF2	Uses contents of FSR2 to address data memory – value of FSR2 not changed (not a physical register)								N/A	64, 85
POSTINC2	Uses contents of FSR2 to address data memory – value of FSR2 post-incremented (not a physical register)								N/A	64, 85
POSTDEC2	Uses contents of FSR2 to address data memory – value of FSR2 post-decremented (not a physical register)								N/A	64, 85
PREINC2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register)								N/A	64, 85
PLUSW2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register), value of FSR2 offset by W								N/A	64, 85
FSR2H	—	—	—	—	Indirect Data Memory Address Pointer 2 High Byte				---- xxxx	64, 85
FSR2L	Indirect Data Memory Address Pointer 2 Low Byte								xxxx xxxx	64, 85
STATUS	—	—	—	N	OV	Z	DC	C	---x xxxx	64, 83

Legend: x = unknown, u = unchanged, - = unimplemented, q = value depends on condition. Shaded locations are unimplemented, read as '0'.

Note 1: The SBOREN bit is only available when the BOREN<1:0> Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 5.4 "Brown-out Reset (BOR)"**.

2: These registers and/or bits are not implemented on 64-pin devices, read as '0'.

3: The PLLEN bit is only available in specific oscillator configurations; otherwise, it is disabled and reads as '0'. See **Section 3.6.4 "PLL in INTOSC Modes"**.

4: The RG5 bit is only available when Master Clear is disabled (MCLRE Configuration bit = 0); otherwise, RG5 reads as '0'. This bit is read-only.

5: RA6/RA7 and their associated latch and direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

6: STKFUL and STKUNF bits are cleared by user software or by a POR.

NOTES:

10.4 IPR Registers

The IPR registers contain the individual priority bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are three Peripheral Interrupt Priority registers (IPR1, IPR2, IPR3). Using the priority bits requires that the Interrupt Priority Enable (IPEN) bit be set.

REGISTER 10-10: IPR1: PERIPHERAL INTERRUPT PRIORITY REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
PSPIP	ADIP	RC1IP	TX1IP	SSPIP	CCP1IP	TMR2IP	TMR1IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **PSPIP:** Parallel Slave Port Read/Write Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **ADIP:** A/D Converter Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **RC1IP:** EUSART Receive Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **TX1IP:** EUSART Transmit Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **SSPIP:** Master Synchronous Serial Port Interrupt Priority bit
1 = High priority
0 = Low priority'

bit 2 **CCP1IP:** CCP1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR2IP:** TMR2 to PR2 Match Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **TMR1IP:** TMR1 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

TABLE 11-7: PORTD FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RD0/AD0/PSP0	RD0	0	O	DIG	LATD<0> data output.
		1	I	ST	PORTD<0> data input.
	AD0(2)	x	O	DIG	External memory interface, Address/Data Bit 0 output.(1)
		x	I	TTL	External memory interface, Data Bit 0 input.(1)
	PSP0	x	O	DIG	PSP read data output (LATD<0>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD1/AD1/PSP1	RD1	0	O	DIG	LATD<1> data output.
		1	I	ST	PORTD<1> data input.
	AD1(2)	x	O	DIG	External memory interface, Address/Data Bit 1 output.(1)
		x	I	TTL	External memory interface, Data Bit 1 input.(1)
	PSP1	x	O	DIG	PSP read data output (LATD<1>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD2/AD2/PSP2	RD2	0	O	DIG	LATD<2> data output.
		1	I	ST	PORTD<2> data input.
	AD2(2)	x	O	DIG	External memory interface, Address/Data Bit 2 output.(1)
		x	I	TTL	External memory interface, Data Bit 2 input.(1)
	PSP2	x	O	DIG	PSP read data output (LATD<2>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD3/AD3/PSP3	RD3	0	O	DIG	LATD<3> data output.
		1	I	ST	PORTD<3> data input.
	AD3(2)	x	O	DIG	External memory interface, Address/Data Bit 3 output.(1)
		x	I	TTL	External memory interface, Data Bit 3 input.(1)
	PSP3	x	O	DIG	PSP read data output (LATD<3>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD4/AD4/PSP4	RD4	0	O	DIG	LATD<4> data output.
		1	I	ST	PORTD<4> data input.
	AD4(2)	x	O	DIG	External memory interface, Address/Data Bit 4 output.(1)
		x	I	TTL	External memory interface, Data Bit 4 input.(1)
	PSP4	x	O	DIG	PSP read data output (LATD<4>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD5/AD5/PSP5	RD5	0	O	DIG	LATD<5> data output.
		1	I	ST	PORTD<5> data input.
	AD5(2)	x	O	DIG	External memory interface, Address/Data Bit 5 output.(1)
		x	I	TTL	External memory interface, Data Bit 5 input.(1)
	PSP5	x	O	DIG	PSP read data output (LATD<5>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD6/AD6/PSP6	RD6	0	O	DIG	LATD<6> data output.
		1	I	ST	PORTD<6> data input.
	AD6(2)	x	O	DIG-3	External memory interface, Address/Data Bit 6 output.(1)
		x	I	TTL	External memory interface, Data Bit 6 input.(1)
	PSP6	x	O	DIG	PSP read data output (LATD<6>); takes priority over port data.
		x	I	TTL	PSP write data input.

Legend: O = Output, I = Input, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: External memory interface I/O takes priority over all other digital and PSP I/O.

2: Implemented on 80-pin devices only.

15.0 TIMER3 MODULE

The Timer3 timer/counter module incorporates these features:

- Software-selectable operation as a 16-bit timer or counter
- Readable and writable 8-bit registers (TMR3H and TMR3L)
- Selectable clock source (internal or external), with device clock or Timer1 oscillator internal options
- Interrupt-on-overflow
- Module Reset on CCP Special Event Trigger

A simplified block diagram of the Timer3 module is shown in Figure 15-1. A block diagram of the module's operation in Read/Write mode is shown in Figure 15-2.

The Timer3 module is controlled through the T3CON register (Register 15-1). It also selects the clock source options for the CCP modules (see **Section 16.1.1 "CCP Modules and Timer Resources"** for more information).

REGISTER 15-1: T3CON: TIMER3 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{\text{T3SYNC}}$	TMR3CS	TMR3ON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **RD16:** 16-Bit Read/Write Mode Enable bit
1 = Enables register read/write of Timer3 in one 16-bit operation
0 = Enables register read/write of Timer3 in two 8-bit operations

bit 6, 3 **T3CCP<2:1>:** Timer3 and Timer1 to CCPx Enable bits
11 = Timer3 is the clock source for compare/capture of all CCP modules
10 = Timer3 is the clock source for compare/capture of CCP3,
Timer1 is the clock source for compare/capture of CCP1 and CCP2
01 = Timer3 is the clock source for compare/capture of CCP2 and CCP3,
Timer1 is the clock source for compare/capture of CCP1
00 = Timer1 is the clock source for compare/capture of all CCP modules

bit 5-4 **T3CKPS<1:0>**: Timer3 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 2 **T3SYNC:** Timer3 External Clock Input Synchronization Control bit
(Not usable if the device clock comes from Timer1/Timer3.)
When TMR3CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR3CS = 0:
This bit is ignored. Timer3 uses the internal clock when TMR3CS = 0.

bit 1 **TMR3CS:** Timer3 Clock Source Select bit
1 = External clock input from Timer1 oscillator or T13CKI (on the rising edge after the first falling edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR3ON:** Timer3 On bit
1 = Enables Timer3
0 = Stops Timer3

16.2.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit, CCP2IE (PIE2<1>), clear to avoid false interrupts and should clear the flag bit, CCP2IF, following any such change in operating mode.

16.2.4 CCP PRESCALER

There are four prescaler settings in Capture mode; they are specified as part of the operating mode selected by the mode select bits (CCP2M<3:0>). Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore, the first capture may be from a non-zero prescaler. Example 16-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 16-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF   CCP2CON      ; Turn CCP module off
MOVLW  NEW_CAPT_PS  ; Load WREG with the
                    ; new prescaler mode
                    ; value and CCP ON
MOVWF  CCP2CON      ; Load CCP2CON with
                    ; this value
```

16.3 Compare Mode

In Compare mode, the 16-bit CCPR2 register value is constantly compared against either the TMR1 or TMR3 register pair value. When a match occurs, the CCP2 pin can be:

- driven high
- driven low
- toggled (high-to-low or low-to-high)
- remain unchanged (that is, reflects the state of the I/O latch)

The action on the pin is based on the value of the mode select bits (CCP2M<3:0>). At the same time, the interrupt flag bit, CCP2IF, is set.

16.3.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the appropriate TRIS bit.

Note:	Clearing the CCPxCON register will force the RC1 or RE7 compare output latch (depending on device configuration) to the default low level. This is not the PORTC or PORTE I/O data latch.

16.3.2 TIMER1/TIMER3 MODE SELECTION

Timer1 and/or Timer3 must be running in Timer mode, or Synchronized Counter mode, if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

16.3.3 SOFTWARE INTERRUPT MODE

When the Generate Software Interrupt mode is chosen (CCP2M<3:0> = 1010), the CCP2 pin is not affected. Only a CCP interrupt is generated if enabled and the CCP2IE bit is set.

16.3.4 SPECIAL EVENT TRIGGERS

CCP1 and CCP2 are both equipped with a Special Event Trigger. This is an internal hardware signal, generated in Compare mode, to trigger actions by other modules. The Special Event Trigger is enabled by selecting the Compare Special Event Trigger mode (CCP2M<3:0> = 1011).

For either CCP module, the Special Event Trigger resets the Timer register pair for whichever timer resource is currently assigned as the module’s time base. This allows the CCPRx registers to serve as a programmable period register for either timer.

The Special Event Trigger for CCP2 can also start an A/D conversion. In order to do this, the A/D Converter must already be enabled.

Note:	The Special Event Trigger of CCP1 only resets Timer1/Timer3 and cannot start an A/D conversion even when the A/D Converter is enabled.

CCP3 is not equipped with a Special Event Trigger. Selecting the Compare Special Event Trigger mode for this device (CCP3M<3:0> = 1011) is functionally the same as selecting the Generate Software Interrupt mode (CCP3M<3:0> = 1010).

20.8 Use of the CCP2 Trigger

An A/D conversion can be started by the "Special Event Trigger" of the CCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH/ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate TACQ time selected before the "Special Event Trigger" sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the "Special Event Trigger" will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 20-2: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	63
PIR1	PSPIF	ADIF	RC1IF	TX1IF	SSPIF	CCP1IF	TMR2IF	TMR1IF	65
PIE1	PSPIE	ADIE	RC1IE	TX1IE	SSPIE	CCP1IE	TMR2IE	TMR1IE	65
IPR1	PSPIP	ADIP	RC1IP	TX1IP	SSPIP	CCP1IP	TMR2IP	TMR1IP	65
PIR2	OSCFIF	CMIF	—	—	BCLIF	HLVDIF	TMR3IF	CCP2IF	65
PIE2	OSCFIE	CMIE	—	—	BCLIE	HLVDIE	TMR3IE	CCP2IE	65
IPR2	OSCFIP	CMIP	—	—	BCLIP	HLVDIP	TMR3IP	CCP2IP	65
ADRESH	A/D Result Register High Byte								64
ADRESL	A/D Result Register Low Byte								64
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	64
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	64
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	64
PORTA	RA7(1)	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	66
TRISA	TRISA7(1)	TRISA6(1)	PORTA Data Direction Register						66
PORTF	RF7	RF6	RF5	RF4	RF3	RF2	RF1	RF0	66
TRISF	PORTF Data Direction Register								66
LATF	LATF Output Latch Register								66

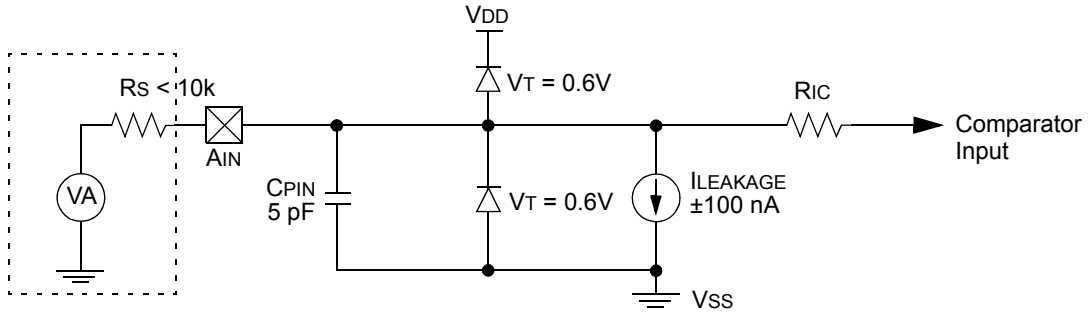
Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: These pins may be configured as port pins depending on the oscillator mode selected.

21.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 21-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up condition may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 21-4: COMPARATOR ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
VT = Threshold Voltage
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage

TABLE 21-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	65
CVRCON	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	65
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	63
PIR2	OSCFIF	CMIF	—	—	BCLIF	HLVDIF	TMR3IF	CCP2IF	65
PIE2	OCSFIE	CMIE	—	—	BCLIE	HLVDIE	TMR3IE	CCP2IE	65
IPR2	OSCFIP	CMIP	—	—	BCLIP	HLVDIP	TMR3IP	CCP2IP	65
PORTF	RF7	RF6	RF5	RF4	RF3	RF2	RF1	RF0	66
LATF	LATF Output Latch Register								66
TRISF	PORTF Data Direction Register								66

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the comparator module.

22.0 COMPARATOR VOLTAGE REFERENCE MODULE

The comparator voltage reference is a 16-tap resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it may also be used independently of them.

A block diagram is of the module shown in Figure 22-1. The resistor ladder is segmented to provide two ranges of CVREF values and has a power-down function to conserve power when the reference is not being used. The module's supply reference can be provided from either device VDD/VSS, or an external voltage reference.

22.1 Configuring the Comparator Voltage Reference

The voltage reference module is controlled through the CVRCON register (Register 22-1). The Comparator Voltage Reference provides two ranges of output voltage, each with 16 distinct levels. The range to be used is selected by the CVRR bit (CVRCON<5>). The primary difference between the ranges is the size of the steps selected by the CVREF selection bits (CVR<3:0>), with one range offering finer resolution. The equations used to calculate the output of the Comparator Voltage Reference are as follows:

If CVRR = 1:

CVREF = ((CVR<3:0>)/24) x CVRSRC

If CVRR = 0:

CVREF = (CVDD x 1/4) + (((CVR<3:0>)/32) x CVRSRC)

The comparator reference supply voltage can come from either VDD and VSS, or the external VREF+ and VREF- that are multiplexed with RA2 and RA3. The voltage source is selected by the CVRSS bit (CVRCON<4>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output (see Table 27-3 in **Section 27.0 "Electrical Characteristics"**).

REGISTER 22-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVROE(1)	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CVREN**: Comparator Voltage Reference Enable bit
1 = CVREF circuit powered on
0 = CVREF circuit powered down

bit 6 **CVROE**: Comparator VREF Output Enable bit(1)
1 = CVREF voltage level is also output on the RF5/AN10/CVREF pin
0 = CVREF voltage is disconnected from the RF5/AN10/CVREF pin

bit 5 **CVRR**: Comparator VREF Range Selection bit
1 = 0 CVRSRC to 0.667 CVRSRC, with CVRSRC/24 step size
0 = 0.25 CVRSRC to 0.75 CVRSRC, with CVRSRC/32 step size

bit 4 **CVRSS**: Comparator VREF Source Selection bit
1 = Comparator reference source, CVRSRC = (VREF+) – (VREF-)
0 = Comparator reference source, CVRSRC = VDD – VSS

bit 3-0 **CVR<3:0>:** Comparator VREF Value Selection bits (0 ≤ (CVR<3:0>) ≤ 15)
When CVRR = 1:
CVREF = ((CVR<3:0>)/24) • (CVRSRC)
When CVRR = 0:
CVREF = (CVRSRC/4) + ((CVR<3:0>)/32) • (CVRSRC)

Note 1: CVROE overrides the TRISF<5> bit setting if enabled for output; RF5 must also be configured as an input by setting TRISF<5> to '1'.

23.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

PIC18F6310/6410/8310/8410 devices have a High/Low-Voltage Detect module (HLVD). This is a programmable circuit that allows the user to specify both a device voltage trip point and the direction of change from that point. If the device experiences an excursion past the trip point in that direction, an interrupt flag is set. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The High/Low-Voltage Detect Control register (Register 23-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

The block diagram for the HLVD module is shown in Figure 23-1.

REGISTER 23-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
VDIRMAG	—	IRVST	HLVDEN	HLVDL3(1)	HLVDL2(1)	HLVDL1(1)	HLVDL0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **VDIRMAG:** Voltage Direction Magnitude Select bit
1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>)
0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)

bit 6 **Unimplemented:** Read as '0'

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage range
0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage range and the HLVD interrupt should not be enabled

bit 4 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD is enabled
0 = HLVD is disabled

bit 3-0 **HLVDL<3:0>:** Voltage Detection Limit bits(1)
1110 = Maximum setting
•
•
•
0001 = Minimum setting

Note 1: HLVDL<3:0> modes that result in a trip point, below the valid operating voltage of the device, are not tested.

24.3 Two-Speed Start-up

The Two-Speed Start-up feature helps to minimize the latency period from oscillator start-up to code execution by allowing the microcontroller to use the INTRC oscillator as a clock source until the primary clock source is available. It is enabled by setting the IESO Configuration bit.

Two-Speed Start-up should be enabled only if the primary oscillator mode is LP, XT, HS or HSPLL (Crystal-Based modes). Other sources do not require a OST start-up delay; for these, Two-Speed Start-up should be disabled.

When enabled, Resets and wake-ups from Sleep mode cause the device to configure itself to run from the internal oscillator block as the clock source, following the time-out of the Power-up Timer after a Power-on Reset is enabled. This allows almost immediate code execution while the primary oscillator starts and the OST is running. Once the OST times out, the device automatically switches to PRI_RUN mode.

To use a higher clock speed on wake-up, the INTOSC or postscaler clock sources can be selected to provide a higher clock speed by setting bits, IRCF<2:0>, immediately after Reset. For wake-ups from Sleep, the INTOSC or postscaler clock sources can be selected by setting the IRCF<2:0> bits prior to entering Sleep mode.

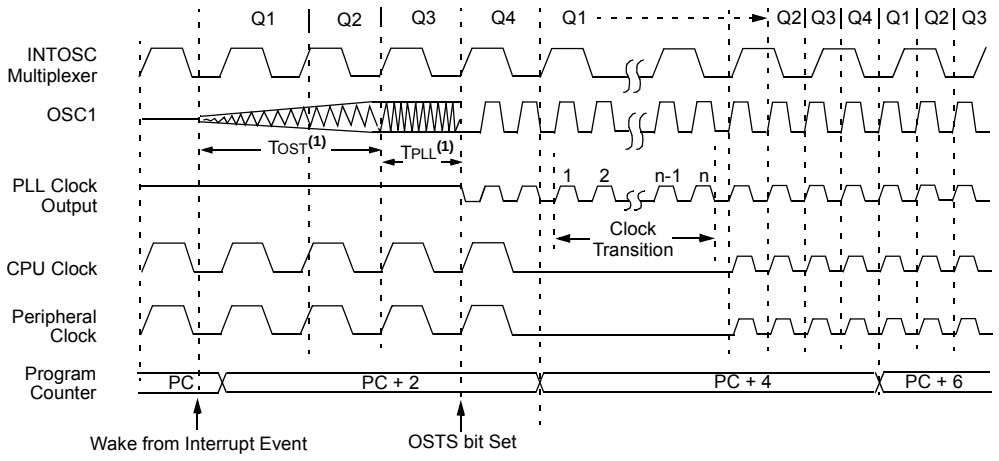
In all other power-managed modes, Two-Speed Start-up is not used. The device will be clocked by the currently selected clock source until the primary clock source becomes available. The setting of the IESO bit is ignored.

24.3.1 SPECIAL CONSIDERATIONS FOR USING TWO-SPEED START-UP

While using the INTRC oscillator in Two-Speed Start-up, the device still obeys the normal command sequences for entering power-managed modes, including serial SLEEP instructions (refer to **Section 4.1.2 "Entering Power-Managed Modes"**). In practice, this means that user code can change the SCS<1:0> bits setting or issue SLEEP instructions before the OST times out. This would allow an application to briefly wake-up, perform routine "housekeeping" tasks and return to Sleep before the device starts to operate from the primary oscillator.

User code can also check if the primary clock source is currently providing the device clocking by checking the status of the OSTS bit (OSCCON<3>). If the bit is set, the primary oscillator is providing the clock. Otherwise, the internal oscillator block is providing the clock during wake-up from Reset or Sleep mode.

FIGURE 24-2: TIMING TRANSITION FOR TWO-SPEED START-UP (INTOSC TO HSPLL)



Note 1: TOST = 1024 TOSC; TPLL = 2 ms (approx). These intervals are not shown to scale.

MULLW **Multiply literal with W**

Syntax: MULLW k

Operands: $0 \le k \le 255$

Operation: (W) x k → PRODH:PRODL

Status Affected: None

Encoding:

0000	1101	kkkk	kkkk

Description: An unsigned multiplication is carried out between the contents of W and the 8-bit literal 'k'. The 16-bit result is placed in PRODH:PRODL register pair. PRODH contains the high byte.
W is unchanged.
None of the Status flags are affected.
Note that neither Overflow nor Carry is possible in this operation. A Zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write registers PRODH: PRODL

Example: MULLW 0C4h

Before Instruction
W = E2h
PRODH = ?
PRODL = ?
After Instruction
W = E2h
PRODH = ADh
PRODL = 08h

MULWF **Multiply W with f**

Syntax: MULWF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (W) x (f) → PRODH:PRODL

Status Affected: None

Encoding:

0000	001a	ffff	ffff

Description: An unsigned multiplication is carried out between the contents of W and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte. Both W and 'f' are unchanged.
None of the Status flags are affected. Note that neither Overflow nor Carry is possible in this operation. A Zero result is possible but not detected.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write registers PRODH: PRODL

Example: MULWF REG, 1

Before Instruction
W = C4h
REG = B5h
PRODH = ?
PRODL = ?
After Instruction
W = C4h
REG = B5h
PRODH = 8Ah
PRODL = 94h

TSTFSZ **Test f, skip if 0**

Syntax: TSTFSZ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: skip if f = 0

Status Affected: None

Encoding:

0110	011a	ffff	ffff

Description: If 'f' = 0, the next instruction, fetched during the current instruction execution, is discarded and a NOP is executed, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    TSTFSZ  CNT, 1
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
If CNT = 00h,
PC = Address (ZERO)
If CNT ≠ 00h,
PC = Address (NZERO)

XORLW **Exclusive OR literal with W**

Syntax: XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. $k \rightarrow W$

Status Affected: N, Z

Encoding:

0000	1010	kkkk	kkkk

Description: The contents of W are XORed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example:
```
XORLW   0AFh
```
Before Instruction
W = B5h
After Instruction
W = 1Ah

FIGURE 27-7: CLKO AND I/O TIMING

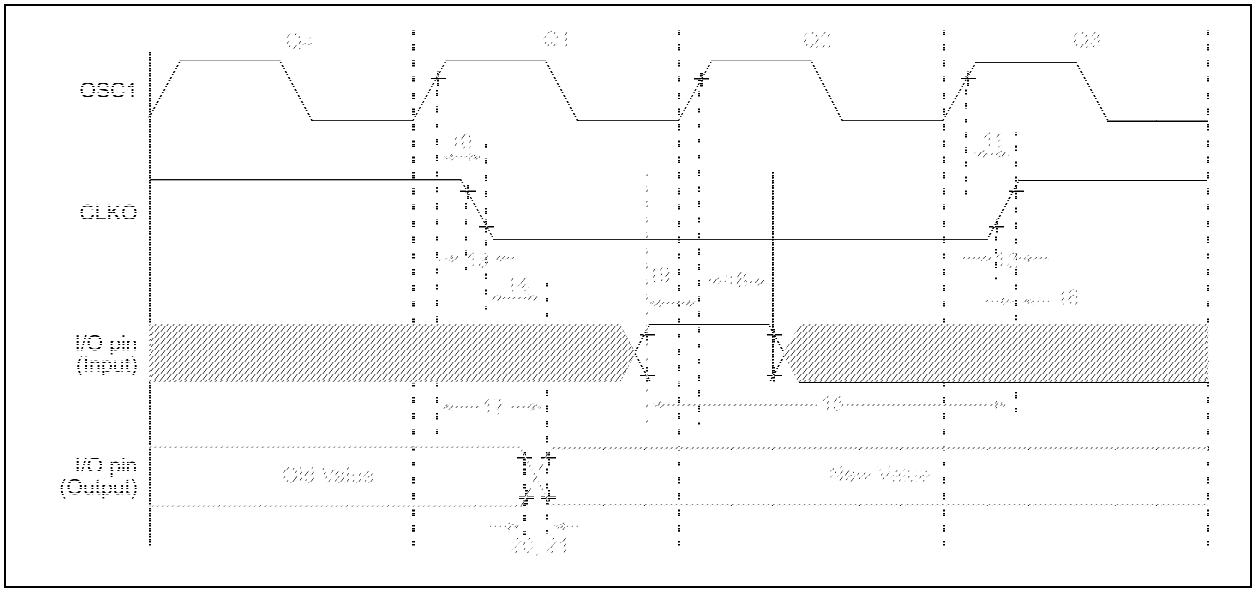


TABLE 27-9: CLKO AND I/O TIMING REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
10	TosH2ckL	OSC1 ↑ to CLKO ↓		—	75	200	ns	**(Note 1)**
11	TosH2ckH	OSC1 ↑ to CLKO ↑		—	75	200	ns	**(Note 1)**
12	TckR	CLKO Rise Time		—	35	100	ns	**(Note 1)**
13	TckF	CLKO Fall Time		—	35	100	ns	**(Note 1)**
14	TckL2ioV	CLKO ↓ to Port Out Valid		—	—	0.5 TCY + 20	ns	**(Note 1)**
15	TioV2ckH	Port In Valid before CLKO ↑		0.25 TCY + 25	—	—	ns	**(Note 1)**
16	TckH2ioI	Port In Hold after CLKO ↑		0	—	—	ns	**(Note 1)**
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port Out Valid		—	50	150	ns	
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port Input Invalid (I/O in hold time)	PIC18**F**XXXX	100	—	—	ns	
18A			PIC18**LF**XXXX	200	—	—	ns	VDD = 2.0V
19	TioV2osH	Port Input Valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20	TioR	Port Output Rise Time	PIC18**F**XXXX	—	10	25	ns	
20A			PIC18**LF**XXXX	—	—	60	ns	VDD = 2.0V
21	TioF	Port Output Fall Time	PIC18**F**XXXX	—	10	25	ns	
21A			PIC18**LF**XXXX	—	—	60	ns	VDD = 2.0V
22†	Tinp	INTx pin High or Low Time		TCY	—	—	ns	
23†	Trbp	RB<7:4> Change INTx High or Low Time		TCY	—	—	ns	

† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC mode, where CLKO output is 4 x TOSC.

PIC18F6310/6410/8310/8410 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC18F6310/6410/8310/8410[(1)]; PIC18F6310/6410/8310/8410T[(2)]; VDD range 4.2V to 5.5V PIC18LF6310/6410/8310/8410[(1)]; PIC18LF6310/6410/8310/8410T[(2)]; VDD range 2.0V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	PT = TQFP (Thin Quad Flatpack)
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF6410-I/PT 301 = Industrial temp., TQFP package, Extended VDD limits, QTP pattern #301.

b) PIC18F8410-I/PT = Industrial temp., TQFP package, normal VDD limits.

c) PIC18F8410-E/PT = Extended temp., TQFP package, normal VDD limits.

Note 1: F = Standard Voltage Range
LF = Wide Voltage Range
2: T = in tape and reel